

6810 - Std-3D Packaging and Integration

6810 - Std-3D Packaging and Integration Reapproval of SEMI 3D13-0715, Guide for Measuring Voids in Bonded Wafer Stacks

AbstainComments	AFF_FabConsult	49571 - Bouldin, David
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2.1 Scope: It specifically mentions that this Guide only covers commercial instruments available in the 2012-2014 time frame. It seems that this Guide should be updated to apply to more current instruments that are not almost 10 years old.		
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Total Voting Interests/Votes: 116/136**Voting Interest Accepts: 56 (100.00%)****No Rejects****Voting Interest Returns: 64****Return Percentage: 62.75%****Voting Interest Distribution: 102**

6811 - Std-3D Packaging and Integration

6811 - Std-3D Packaging and Integration Reapproval of SEMI 3D2-0216, Specification for Glass Carrier Wafers for 3DS-IC Applications

Total Voting Interests/Votes: 116/136**Voting Interest Accepts: 55 (100.00%)****No Rejects****Voting Interest Returns: 64****Return Percentage: 62.75%****Voting Interest Distribution: 102**

6812 - Std-3D Packaging and Integration

6812 - Std-3D Packaging and Integration Reapproval of SEMI 3D4-0915, Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks

Total Voting Interests/Votes: 116/136**Voting Interest Accepts: 56 (100.00%)****No Rejects****Voting Interest Returns: 64****Return Percentage: 62.75%****Voting Interest Distribution: 102**